



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c621-04i-so

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

Table of Contents

1.0	General Description	. 5
2.0	PIC16C62X Device Varieties	. 7
3.0	Architectural Overview	. 9
4.0	Memory Organization	13
5.0	I/O Ports	25
6.0	Timer0 Module	31
7.0	Comparator Module	37
8.0	Voltage Reference Module	43
9.0	Special Features of the CPU	45
10.0	Instruction Set Summary	61
11.0	Development Support	75
12.0	Electrical Specifications	81
13.0	Device Characterization Information	09
14.0	Packaging Information 1	13
Append	Jix A: Enhancements 1	19
Append	dix B: Compatibility 1	19
Index		21
On-Line	e Support 1	23
System	Information and Upgrade Hot Line	23
Reader	r Response 1	24
Produc	t Identification System 1	25

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@mail.microchip.com** or fax the **Reader Response Form** in the back of this data sheet to (480) 792-4150. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000A is version A of document DS30000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; http://www.microchip.com
- Your local Microchip sales office (see last page)
- The Microchip Corporate Literature Center; U.S. FAX: (480) 792-7277

When contacting a sales office or the literature center, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at www.microchip.com/cn to receive the most current information on all of our products.

3.1 Clocking Scheme/Instruction Cycle

The clock input (OSC1/CLKIN pin) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3 and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow is shown in Figure 3-2.

3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3 and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g., GOTO) then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3 and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).



FIGURE 3-2: CLOCK/INSTRUCTION CYCLE

EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



4.2.2 SPECIAL FUNCTION REGISTERS

The Special Function Registers are registers used by the CPU and Peripheral functions for controlling the desired operation of the device (Table 4-1). These registers are static RAM. The Special Function Registers can be classified into two sets (core and peripheral). The Special Function Registers associated with the "core" functions are described in this section. Those related to the operation of the peripheral features are described in the section of that peripheral feature.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS ⁽¹⁾
Bank 0											
00h	INDF	Addressin register)	ig this locat	on uses co	ntents of FS	SR to addre	ess data me	mory (not a	a physical	XXXX XXXX	XXXX XXXX
01h	TMR0	Timer0 Mo	odule's Reg	ister						xxxx xxxx	uuuu uuuu
02h	PCL	Program (Counter's (F	PC) Least S	Significant B	yte				0000 0000	0000 0000
03h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
04h	FSR	Indirect da	ata memory	address po	ointer					xxxx xxxx	uuuu uuuu
05h	PORTA	—	—	—	RA4	RA3	RA2	RA1	RA0	x 0000	u 0000
06h	PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	xxxx xxxx	uuuu uuuu
07h-09h	Unimplemented									_	_
0Ah	PCLATH	—	—	—	Write buffe	er for upper	5 bits of pr	ogram coui	nter	0 0000	0 0000
0Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	—	—	—	—	—	—	-0	-0
0Dh-1Eh	Unimplemented									_	_
1Fh	CMCON	C2OUT	C10UT	—	—	CIS	CM2	CM1	CM0	00 0000	00 0000
Bank 1											
80h	INDF	Addressin register)	g this locat	ion uses co	ntents of FS	SR to addre	ess data me	mory (not a	a physical	xxxx xxxx	xxxx xxxx
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
82h	PCL	Program (Counter's (F	PC) Least S	ignificant B	yte				0000 0000	0000 0000
83h	STATUS	IRP ⁽²⁾	RP1 ⁽²⁾	RP0	TO	PD	Z	DC	С	0001 1xxx	000q quuu
84h	FSR	Indirect da	ata memory	address po	ointer					xxxx xxxx	uuuu uuuu
85h	TRISA	-	-	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111
86h	TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	1111 1111	1111 1111
87h-89h	Unimplemented									_	_
8Ah	PCLATH	-	-	—	Write buffe	er for upper	5 bits of pr	ogram coui	nter	0 0000	0 0000
8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
8Ch	PIE1	—	CMIE	—	—	—	—	—	—	-0	-0
8Dh	Unimplemented									_	_
8Eh	PCON	_	_	_	_	—	_	POR	BOR	0x	uq
8Fh-9Eh	Unimplemented								-	_	_
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000

TABLE 4-1: SPECIAL REGISTERS FOR THE PIC16C62X

Legend: — = Unimplemented locations read as '0', u = unchanged, x = unknown,

 ${\rm q}$ = value depends on condition, shaded = unimplemented

Note 1: Other (non Power-up) Resets include MCLR Reset, Brown-out Reset and Watchdog Timer Reset during normal operation.

2: IRP & RP1 bits are reserved; always maintain these bits clear.









TABLE 7-1 :	REGISTERS ASSOCIATED WITH COMPARATOR MODULE
--------------------	--

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
1Fh	CMCON	C2OUT	C10UT			CIS	CM2	CM1	CM0	00 0000	00 0000
9Fh	VRCON	VREN	VROE	VRR	_	VR3	VR2	VR1	VR0	000- 0000	000- 0000
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1		CMIF		_	_			_	-0	-0
8Ch	PIE1	_	CMIE	_	_	_	_	_	_	-0	-0
85h	TRISA		_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111

Legend: x = unknown, u = unchanged, - = unimplemented, read as "0"

-

9.3 RESET

The PIC16C62X differentiates between various kinds of RESET:

- a) Power-on Reset (POR)
- b) MCLR Reset during normal operation
- c) MCLR Reset during SLEEP
- d) WDT Reset (normal operation)
- e) WDT wake-up (SLEEP)
- f) Brown-out Reset (BOR)

Some registers are not affected in any RESET condition Their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-on Reset,

MCLR Reset, WDT Reset and MCLR Reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. TO and PD bits are set or cleared differently in different RESET situations as indicated in Table 9-2. These bits are used in software to determine the nature of the RESET. See Table 9-5 for a full description of RESET states of all registers.

A simplified block diagram of the on-chip RESET circuit is shown in Figure 9-6.

The $\overline{\text{MCLR}}$ Reset path has a noise filter to detect and ignore small pulses. See Table 12-5 for pulse width specification.





TABLE 9-4: INITIALIZATION CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	0x
MCLR Reset during normal operation	000h	000u uuuu	uu
MCLR Reset during SLEEP	000h	0001 0uuu	uu
WDT Reset	000h	0000 uuuu	uu
WDT Wake-up	PC + 1	uuu0 0uuu	uu
Brown-out Reset	000h	000x xuuu	u0
Interrupt Wake-up from SLEEP	PC + 1 ⁽¹⁾	uuul 0uuu	uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, reads as '0'.

Note 1: When the wake-up is due to an interrupt and global enable bit, GIE is set, the PC is loaded with the interrupt vector (0004h) after execution of PC+1.

Register	Address	Power-on Reset	MCLR Reset during normal operation MCLR Reset during SLEEP WDT Reset Brown-out Reset ⁽¹⁾	 Wake-up from SLEEP through interrupt Wake-up from SLEEP through WDT time-out
W		****		1111111 1111111
INDF	00h		_	_
TMR0	01h	xxxx xxxx	<u>uuuu</u> uuuu	<u>uuuu</u> uuuu
PCL	02h	0000 0000	0000 0000	PC + 1 ⁽³⁾
STATUS	03h	0001 1xxx	000q quuu ⁽⁴⁾	uuuq quuu ⁽⁴⁾
FSR	04h	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	05h	x xxxx	u uuuu	u uuuu
PORTB	06h	xxxx xxxx	uuuu uuuu	uuuu uuuu
CMCON	1Fh	00 0000	00 0000	uu uuuu
PCLATH	0Ah	0 0000	0 0000	u uuuu
INTCON	0Bh	0000 000x	0000 000u	uuuu uqqq ⁽²⁾
PIR1	0Ch	-0	-0	-q (2,5)
OPTION	81h	1111 1111	1111 1111	սսսս սսսս
TRISA	85h	1 1111	1 1111	u uuuu
TRISB	86h	1111 1111	1111 1111	սսսս սսսս
PIE1	8Ch	-0	-0	-u
PCON	8Eh	0x	uq ^(1,6)	uu
VRCON	9Fh	000- 0000	000- 0000	uuu- uuuu

TABLE 9-5: INITIALIZATION CONDITION FOR REGISTERS

 $\label{eq:legend: u = unchanged, x = unknown, - = unimplemented bit, reads as `0', q = value depends on condition.$

Note 1: If VDD goes too low, Power-on Reset will be activated and registers will be affected differently.

2: One or more bits in INTCON, PIR1 and/or PIR2 will be affected (to cause wake-up).

3: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

4: See Table 9-4 for RESET value for specific condition.

5: If wake-up was due to comparator input changing, then bit 6 = 1. All other interrupts generating a wake-up will cause bit 6 = u.

6: If RESET was due to brown-out, then bit 0 = 0. All other RESETS will cause bit 0 = u.

9.5 Interrupts

The PIC16C62X has 4 sources of interrupt:

- External interrupt RB0/INT
- TMR0 overflow interrupt
- PORTB change interrupts (pins RB<7:4>)
- · Comparator interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. Individual interrupts can be disabled through their corresponding enable bits in INTCON register. GIE is cleared on RESET.

The "return from interrupt" instruction, RETFIE, exits interrupt routine, as well as sets the GIE bit, which reenable RB0/INT interrupts.

The INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flag is contained in the special register PIR1. The corresponding interrupt enable bit is contained in special registers PIE1.

When an interrupt is responded to, the GIE is cleared to disable any further interrupt, the return address is pushed into the stack and the PC is loaded with 0004h.

FIGURE 9-15: INTERRUPT LOGIC

Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid RB0/ INT recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 9-16). The latency is the same for one or two cycle instructions. Once in the interrupt service routine, the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid multiple interrupt requests.

- Note 1: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.
 - 2: When an instruction that clears the GIE bit is executed, any interrupts that were pending for execution in the next cycle are ignored. The CPU will execute a NOP in the cycle immediately following the instruction which clears the GIE bit. The interrupts which were ignored are still pending to be serviced when the GIE bit is set again.



9.7 Watchdog Timer (WDT)

The Watchdog Timer is a free running on-chip RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the CLKIN pin. That means that the WDT will run, even if the clock on the OSC1 and OSC2 pins of the device has been stopped, for example, by execution of a SLEEP instruction. During normal operation, a WDT time-out generates a device RESET. If the device is in SLEEP mode, a WDT time-out causes the device to wake-up and continue with normal operation. The WDT can be permanently disabled by programming the configuration bit WDTE as clear (Section 9.1).

9.7.1 WDT PERIOD

The WDT has a nominal time-out period of 18 ms, (with no prescaler). The time-out periods vary with temperature, VDD and process variations from part to part (see

DC specs). If longer time-out periods are desired, a prescaler with a division ratio of up to 1:128 can be assigned to the WDT under software control by writing to the OPTION register. Thus, time-out periods up to 2.3 seconds can be realized.

The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device RESET.

The $\overline{\text{TO}}$ bit in the STATUS register will be cleared upon a Watchdog Timer time-out.

9.7.2 WDT PROGRAMMING CONSIDERATIONS

It should also be taken in account that under worst case conditions (VDD = Min., Temperature = Max., max. WDT prescaler) it may take several seconds before a WDT time-out occurs.



FIGURE 9-17: WATCHDOG TIMER BLOCK DIAGRAM

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR Reset	Value on all other RESETS
2007h	Config. bits	—	BODEN	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0	—	—
81h	OPTION	RBPU	INTEDG	TOCS	TOSE	PSA	PS2	PS1	PS0	1111 1111	1111 1111

Legend: Shaded cells are not used by the Watchdog Timer.

Note: – = Unimplemented location, read as "0"

+ = Reserved for future use

9.8 Power-Down Mode (SLEEP)

The Power-down mode is entered by executing a SLEEP instruction.

If enabled, the Watchdog Timer will be cleared but keeps running, the PD bit in the STATUS register is cleared, the TO bit is set, and the oscillator driver is turned off. The I/O ports maintain the status they had, before SLEEP was executed (driving high, low, or hi-impedance).

For lowest current consumption in this mode, all I/O pins should be either at VDD or VSs with no external circuitry drawing current from the I/O pin and the comparators and VREF should be disabled. I/O pins that are hi-impedance inputs should be pulled high or low externally to avoid switching currents caused by floating inputs. The TOCKI input should also be at VDD or VSs for lowest current consumption. The contribution from on chip pull-ups on PORTB should be considered.

The MCLR pin must be at a logic high level (VIHMC).

Note:	It should be noted that a RESET generated					
	by a WDT time-out does not drive MCLR					
	pin low.					

9.8.1 WAKE-UP FROM SLEEP

The device can wake-up from SLEEP through one of the following events:

- 1. External RESET input on MCLR pin
- 2. Watchdog Timer Wake-up (if WDT was enabled)
- 3. Interrupt from RB0/INT pin, RB Port change, or the Peripheral Interrupt (Comparator).

The first event will cause a device RESET. The two latter events are considered a continuation of program execution. The TO and PD bits in the STATUS register can be used to determine the cause of device RESET. PD bit, which is set on power-up, is cleared when SLEEP is invoked. TO bit is cleared if WDT wake-up occurred.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction after the SLEEP instruction after the instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have an NOP after the SLEEP instruction.

Note: If the global interrupts are disabled (GIE is cleared), but any interrupt source has both its interrupt enable bit and the corresponding interrupt flag bits set, the device will immediately wake-up from SLEEP. The SLEEP instruction is completely executed.

The WDT is cleared when the device wakes up from SLEEP, regardless of the source of wake-up.

Q1 Q2 Q3 Q4 Q1 Q2 Q3 Q4	4 Q1	Q1 Q2 Q3 Q4	Q1 Q2 Q3 Q4	Q1 Q2 Q3 Q4	Q1 Q2 Q3 Q4
CLKOUT(4)	Tost(2)/	\/	\/'\	'
INT pin		1	ı ı ı ı	1	I
INTE flag	\		I I		
(INTCON<1>)	·····/	Interrupt Latend	şy		
	<u>i</u>	(Note 2)	i		
(INTCON<7>)	Processor in	1		<u> </u>	<u> </u>
	SLEEP	1	I I	i	i i
INSTRUCTION FLOW		1	і і і і	1	1
PC X PC+1	X PC+2	X PC+2	X PC + 2	<u>x 0004h x</u>	0005h
$\begin{array}{c} \mbox{Instruction} \\ \mbox{fetched} \end{array} \Big\{ \begin{array}{c} \mbox{Inst}(\mbox{PC}) = \mbox{SLEEP} & \mbox{Inst}(\mbox{PC} + 1) \end{array} \right.$		Inst(PC + 2)	 	Inst(0004h)	Inst(0005h)
Instruction { Inst(PC - 1) SLEEP		Inst(PC + 1)	Dummy cycle	Dummy cycle	Inst(0004h)
Note 1: XT, HS or LP Oscillator mode 2: Tos⊤ = 1024Tosc (drawing n	e assumed. ot to scale) This	delay will not be	e there for RC	Osc mode.	

FIGURE 9-18: WAKE-UP FROM SLEEP THROUGH INTERRUPT

3: GIE = '1' assumed. In this case, after wake-up, the processor jumps to the interrupt routine. If GIE = '0', execution will continue in-line.

4: CLKOUT is not available in these Osc modes, but shown here for timing reference.

BCF	Bit Clear f	BTFSC	Bit Test, Skip if Clear			
Syntax:	[<i>label</i>]BCF f,b	Syntax:	[<i>label</i>]BTFSC f,b			
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$	Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$			
Operation:	$0 \rightarrow (f \le b >)$	Operation:	skip if (f) = 0			
Status Affected:	None	Status Affected:	None			
Encoding:	01 00bb bfff ffff	Encoding:	01 10bb bfff ffff			
Description:	Bit 'b' in register 'f' is cleared.	Description:	If bit 'b' in register 'f' is '0', then the			
Words:	1		next instruction is skipped.			
Cycles:	1		tion fetched during the current			
Example	BCF FLAG_REG, 7		instruction execution is discarded, and a NOP is executed instead, making this a two-cycle instruction.			
	Before Instruction FLAG REG = 0xC7					
	After Instruction	Words:	1			
	FLAG REG = 0x47	Cycles:	1(2)			
		Example	HERE BTFSC FLAG,1			
BSF	Bit Set f		TRUE • DE			
Syntax:	[<i>label</i>]BSF f,b		•			
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ 0 \leq b \leq 7 \end{array}$		Before Instruction PC = address HERE			
Operation:	$1 \rightarrow (f \le b >)$		After Instruction			
Status Affected:	None		PC = address TRUE			
Encoding:	01 01bb bfff ffff		if FLAG<1>=1,			
Description:	Bit 'b' in register 'f' is set.		PC = address FALSE			
Words:	1					
Cycles:	1					
Example	BSF FLAG_REG, 7					

Before Instruction FLAG_REG = 0x0A After Instruction

FLAG_REG = 0x8A

MOVF	Move f				
Syntax:	[<i>label</i>] MOVF f,d				
Operands:	$\begin{array}{l} 0 \leq f \leq 127 \\ d \in [0,1] \end{array}$				
Operation:	$(f) \rightarrow (dest)$				
Status Affected:	Z				
Encoding:	00 1000 dfff ffff				
Description:	The contents of register f is moved to a destination dependent upon the status of d. If $d = 0$, destination is W register. If $d = 1$, the destination is file register f itself. $d = 1$ is useful to test a file register since status flag Z is affected.				
Words:	1				
Cycles:	1				
Example	MOVF FSR, 0				
	After Instruction W = value in FSR register Z = 1				
MOVWF	Move W to f				
Syntax:	[<i>label</i>] MOVWF f				
Operands:	$0 \leq f \leq 127$				
Operation:	$(W) \rightarrow (f)$				
Status Affected:	None				
Encoding:	00 0000 1fff ffff				
Description:	Move data from W register to reg- ister 'f'.				
Words:	1				
Cycles:	1				
Example	MOVWF OPTION				
	Before Instruction OPTION = 0xFF W = 0x4F				
	After Instruction OPTION = 0x4F W = 0x4F				

NOP	No Operation				
Syntax:	[label]	NOP			
Operands:	None				
Operation:	No operation				
Status Affected:	None				
Encoding:	00	0000	0xx0	0000	
Description:	No opera	tion.			
Words:	1				
Cycles:	1				
Example	NOP				

OPTION	Load Op	tion Reg	gister	
Syntax:	[label]	OPTION	١	
Operands:	None			
Operation:	$(W) \rightarrow OI$	PTION		
Status Affected:	None			
Encoding:	00	0000	0110	0010
Description: Words: Cycles:	The conte loaded in This instr code com products. able/writa directly ad 1	ents of th the OPT uction is patibility Since O able regis ddress it	te W regis FION regi supporte with PIC PTION is ster, the u	ster are ster. d for 16C5X a read- ser can
Example				
	To main ity with product instruct	tain upv future P s, do no ion.	vard com ICmicro [®] t use thi	ıpatibil- ^ฏ s

NOTES:





12.2 DC Characteristics: PIC16C62XA-04 (Commercial, Industrial, Extended) PIC16C62XA-20 (Commercial, Industrial, Extended) PIC16LC62XA-04 (Commercial, Industrial, Extended)

PIC16C62XA				dard O ating te	perati empera	ng Con ature -4 -4	ditions (unless otherwise stated) $40^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial and $0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial and $40^{\circ}C \leq TA \leq +125^{\circ}C$ for extended
PIC16L	C62XA		Stand Oper	dard O ating te	p erati empera	ng Con ature -4 -4	ditions (unless otherwise stated) $40^{\circ}C \leq TA \leq +85^{\circ}C$ for industrial and $0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial and $0^{\circ}C \leq TA \leq +125^{\circ}C$ for extended
Param. No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
D001	Vdd	Supply Voltage	3.0	-	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D001	Vdd	Supply Voltage	2.5	_	5.5	V	See Figures 12-1, 12-2, 12-3, 12-4, and 12-5
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	_	V	Device in SLEEP mode
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure Power-on Reset	-	Vss	_	V	See section on Power-on Reset for details
D003	VPOR	VDD start voltage to ensure Power-on Reset	-	Vss	_	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	_	-	V/ms	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure Power-on Reset	0.05*	—	_	V/ms	See section on Power-on Reset for details
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared
D005	VBOR	Brown-out Detect Voltage	3.7	4.0	4.35	V	BOREN configuration bit is cleared

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD, MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or Vss.

4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula: Ir = VDD/2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

12.5 DC CHARACTERISTICS: PIC16C620A/C621A/C622A-40⁽⁷⁾ (Commercial) PIC16CR620A-40⁽⁷⁾ (Commercial)

DC CHARACTERISTICS		Standard Operating Conditions (unless otherwise stated) Operating temperature $0^{\circ}C \leq TA \leq +70^{\circ}C$ for commercial					
Param No.	Sym	Characteristic	Min	Тур†	Мах	Unit	Conditions
	VIL	Input Low Voltage					
		I/O ports					
D030		with TTL buffer	Vss	—	0.8V 0.15Vdd	V	VDD = 4.5V to 5.5V, otherwise
D031		with Schmitt Trigger input	Vss		0.2VDD	V	
D032		MCLR, RA4/T0CKI, OSC1 (in RC mode)	Vss	—	0.2Vdd	V	(Note 1)
D033		OSC1 (in XT and HS)	Vss	—	0.3VDD	V	
		OSC1 (in LP)	Vss	_	0.6Vdd - 1.0	V	
	Viн	Input High Voltage					
		I/O ports					
D040		with TTL buffer	2.0V	—	VDD	V	VDD = 4.5V to 5.5V, otherwise
D044		with Ochavitt Triansations t	0.25 VDD + 0.8		VDD		
D041					VDD		
D042		MCLR RA4/TUCKI		_	VDD	V	
D043		OSC1 (A1, HS and LP) OSC1 (in RC mode)		_	VDD	v	(Note 1)
D070	IPURB	PORTB Weak Pull-up Current	50	200	400	μА	$V_{DD} = 5.0V$. VPIN = Vss
	lil	Input Leakage Current ^(2, 3)					
		I/O ports (except PORTA)			±1.0	μA	VSS \leq VPIN \leq VDD, pin at hi-impedance
D060		PORTA	_	_	±0.5	μA	Vss \leq VPIN \leq VDD, pin at hi-impedance
D061		RA4/T0CKI	—	—	±1.0	μA	$Vss \le VPIN \le VDD$
D063		OSC1, MCLR	_	—	±5.0	μA	$Vss \leq VPIN \leq VDD,$ XT, HS and LP osc configuration
	Vol	Output Low Voltage					
D080		I/O ports	_	—	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40° to +85°C
			—	—	0.6	V	IOL = 7.0 mA, VDD = 4.5V, +125°C
D083		OSC2/CLKOUT (RC only)	—	—	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40° to +85°C
		(2)	_		0.6	V	IOL = 1.2 mA, VDD = 4.5V, +125°C
	Vон	Output High Voltage ⁽³⁾					
D090		I/O ports (except RA4)	VDD-0.7	—	—	V	IOH = -3.0 mA, VDD = 4.5V, -40° to +85°C
			VDD-0.7	—	—	V	IOH = -2.5 mA, VDD = 4.5V, +125°C
D092		OSC2/CLKOUT (RC only)	VDD-0.7	—	—	V	IOH = -1.3 mA, VDD = 4.5V, -40° to +85°C
*0450	1/25	On an Duain Ulink Matterna	VDD-0.7	_		V	IOH = -1.0 mA, VDD = 4.5V, +125°C
"D150	VOD	Open Drain High Voltage			8.5	V	RA4 pin
		Output Pins					
D100	Cosc2	OSC2 pin			15	pF	In XT, HS and LP modes when external clock used to drive OSC1
D101	Сю	All I/O pins/OSC2 (in RC mode)			50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C, unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in Active Operation mode are:

OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD, MCLR = VDD; WDT enabled/disabled as specified.
 The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in bi-impedance state and tied to VDD or VSS.

 mode, with all I/O pins in hi-impedance state and tied to VDD or VSs.
 For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/ 2REXT (mA) with REXT in kΩ.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

6: Commercial temperature range only.

7: See Section 12.1 and Section 12.3 for 16C62X and 16CR62X devices for operation between 20 MHz and 40 MHz for valid modified characteristics.

20-Lead Plastic Shrink Small Outline (SS) - 209 mil, 5.30 mm (SSOP)



	Units		INCHES*		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		20			20	
Pitch	р		.026			0.65	
Overall Height	Α	.068	.073	.078	1.73	1.85	1.98
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25
Overall Width	E	.299	.309	.322	7.59	7.85	8.18
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38
Overall Length	D	.278	.284	.289	7.06	7.20	7.34
Foot Length	L	.022	.030	.037	0.56	0.75	0.94
Lead Thickness	С	.004	.007	.010	0.10	0.18	0.25
Foot Angle	¢	0	4	8	0.00	101.60	203.20
Lead Width	В	.010	.013	.015	0.25	0.32	0.38
Mold Draft Angle Top	α	0	5	10	0	5	10
Mold Draft Angle Bottom	β	0	5	10	0	5	10

* Controlling Parameter § Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-150 Drawing No. C04-072

DS30235J-page 116

N
NOP Instruction
0
One-Time-Programmable (OTP) Devices7
OPTION Instruction
OPTION Register
Oscillator Configurations
Oscillator Start-up Timer (OST)50
Р
Package Marking Information
Packaging Information
PCL and PCLATH
PCON Register
PICkit 1 FLASH Starter Kit79
PICSTART Plus Development Programmer77
PIE1 Register
PIR1 Register
Port RB Interrupt
PORTA
PORTB
Power Control/Status Register (PCON)
Power-Down Mode (SLEEP)
Power-On Reset (POR)
Power-up Timer (PWRT)
Prescaler
PRO MATE II Universal Device Programmer
Program Memory Organization
Q
Quick-Turnaround-Production (QTP) Devices
R
RC Oscillator
Reset49
RETFIE Instruction70
RETLW Instruction70
RETURN Instruction70
RLF Instruction71
RRF Instruction71
S

0	
Serialized Quick-Turnaround-Production (SQTP) De	vices 7
SLEEP Instruction	71
Software Simulator (MPLAB SIM)	76
Software Simulator (MPLAB SIM30)	76
Special Features of the CPU	45
Special Function Registers	17
Stack	23
Status Register	18
SUBLW Instruction	72
SUBWF Instruction	72
SWAPF Instruction	73

Т

Timer0	
TIMER0	
TIMER0 (TMR0) Interrupt	
TIMER0 (TMR0) Module	
TMR0 with External Clock	
Timer1	
Switching Prescaler Assignment	35
Timing Diagrams and Specifications	104
TMR0 Interrupt	
TRIS Instruction	73
TRISA	
TRISB	

v

Voltage Reference Module VRCON Register	43 43
W	
Watchdog Timer (WDT)	. 58
WWW, On-Line Support	3
X	
XORLW Instruction	. 73
XORWF Instruction	.73

ON-LINE SUPPORT

Microchip provides on-line support on the Microchip World Wide Web site.

The web site is used by Microchip as a means to make files and information easily available to customers. To view the site, the user must have access to the Internet and a web browser, such as Netscape[®] or Microsoft[®] Internet Explorer. Files are also available for FTP download from our FTP site.

Connecting to the Microchip Internet Web Site

The Microchip web site is available at the following URL:

www.microchip.com

The file transfer site is available by using an FTP service to connect to:

ftp://ftp.microchip.com

The web site and file transfer site provide a variety of services. Users may download files for the latest Development Tools, Data Sheets, Application Notes, User's Guides, Articles and Sample Programs. A variety of Microchip specific business information is also available, including listings of Microchip sales offices, distributors and factory representatives. Other data available for consideration is:

- Latest Microchip Press Releases
- Technical Support Section with Frequently Asked
 Questions
- Design Tips
- Device Errata
- Job Postings
- Microchip Consultant Program Member Listing
- Links to other useful web sites related to Microchip Products
- Conferences for products, Development Systems, technical information and more
- · Listing of seminars and events

SYSTEMS INFORMATION AND UPGRADE HOT LINE

The Systems Information and Upgrade Line provides system users a listing of the latest versions of all of Microchip's development systems software products. Plus, this line provides information on how customers can receive the most current upgrade kits. The Hot Line Numbers are:

1-800-755-2345 for U.S. and most of Canada, and

1-480-792-7302 for the rest of the world.

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

To:	Technical Publications Manag	er Total Pages Sent
RE:	Reader Response	
From	n: Name	
	Company	
	Address	
	City / State / ZIP / Country	
	Telephone: ()	FAX: ()
Appl	ication (optional):	
Wou	ld you like a reply?YN	
Devi	ce: PIC16C62X	_iterature Number: DS30235J
Que	stions:	
1. \	What are the best features of this	document?
-		
<u>-</u>		
2. I	How does this document meet yo	ar hardware and software development needs?
-		
3. [Do you find the organization of thi	s document easy to follow? If not, why?
_		
_		
4. \	What additions to the document d	o you think would enhance the structure and subject?
-		
-		
5. \	What deletions from the documen	t could be made without affecting the overall usefulness?
-		
- 6 I	s there any incorrect or misleadin	a information (what and where)?
0. 1		
-		
7. H	How would you improve this docu	ment?
_		
-		